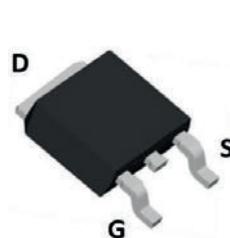
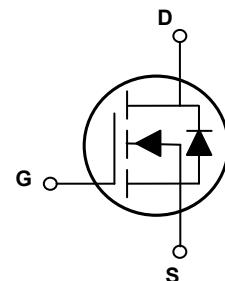


Main Product Characteristics

$V_{(BR)DSS}$	250V
$R_{DS(ON)}$	0.62Ω (Max.)
I_D	6A



TO-252 (DPAK)



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFD2506 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Parameter	Unit
Drain-Source Voltage	V_{DS}	250	V
Gate-to-Source Voltage	V_{GS}	±20	V
Continuous Drain Current, @ Steady-State ($T_C=25^\circ\text{C}$)	I_D	6	A
Continuous Drain Current, @ Steady-State ($T_C=100^\circ\text{C}$)		4.2	A
Pulsed Drain Current ¹	I_{DM}	24	A
Power Dissipation	P_D	38	W
		0.31	W/°C
Single Pulse Avalanche Energy ²	E_{AS}	10.6	mJ
Junction-to-Ambient (PCB Mounted, Steady-State)	R_{JA}	62.5	°C/W
Junction-to-Case	R_{JC}	3.29	°C/W
Operating Junction and Storage Temperature Range	T_J/T_{STG}	-55 to +150	°C
Maximum Lead Temperature for Soldering Purposes	T_L	260	°C

Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On / Off Characteristics						
Drain-to-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	250	-	-	V
Drain-to-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=250\text{V}, V_{\text{GS}}=0\text{V}, T_c=25^\circ\text{C}$	-	-	1.0	μA
		$V_{\text{DS}}=200\text{V}, T_c=125^\circ\text{C}$	-	-	100	μA
Gate-to-Source Forward Leakage	I_{GSS}	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=20\text{V}$	-	-	100	nA
		$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=-20\text{V}$	-	-	-100	
Static Drain-to-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}}=10\text{V}, I_D=2\text{A}$	-	0.53	0.62	Ω
		$V_{\text{GS}}=4.5\text{V}, I_D=2\text{A}$	-	0.59	0.69	
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_D=250\mu\text{A}$	1.0	-	3.0	V
Dynamic and Switching Characteristics						
Input Capacitance	C_{iss}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=25\text{V}, f=1\text{MHz}$	-	777	-	pF
Output Capacitance	C_{oss}		-	14	-	
Reverse Transfer Capacitance	C_{rss}		-	4.6	-	
Total Gate Charge ^{3,4}	Q_g	$I_D=4.0\text{A}, V_{\text{DS}}=100\text{V}, V_{\text{GS}}=10\text{V}$	-	13	-	nC
Gate-to-Source Charge ^{3,4}	Q_{gs}		-	2.3	-	
Gate-to-Drain ("Miller") Charge ^{3,4}	Q_{gd}		-	2.5	-	
Turn-on Delay Time ^{3,4}	$t_{\text{d(on)}}$	$V_{\text{DD}}=100\text{V}, V_{\text{GS}}=10\text{V}, R_G=5\Omega, I_D=5.0\text{A}$	-	14	-	nS
Rise Time ^{3,4}	t_r		-	11	-	
Turn-Off Delay Time ^{3,4}	$t_{\text{d(off)}}$		-	40	-	
Fall Time ^{4,5}	t_f		-	10	-	
Gate Resistance	R_g	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, f=1\text{MHz}$	-	1.6	-	Ω
Source-Drain Ratings and Characteristics						
Continuous Source Current (Body Diode)	I_S	$T_c=25^\circ\text{C}$, MOSFET symbol showing the integral reverse p-n junction diode.	-	-	6.0	A
Diode Pulse Current	I_{SM}		-	-	24	A
Diode Forward Voltage	V_{SD}	$I_S=4.0\text{A}, V_{\text{GS}}=0\text{V}$	-	-	1.3	V
Reverse Recovery Time ³	T_{rr}	$I_S=4.0\text{A}, V_{\text{GS}}=0\text{V}, \frac{dI_F}{dt}=100\text{A}/\mu\text{s}$	-	86	-	nS
Reverse Recovery Charge ³	Q_{rr}		-	0.29	-	μC

Note:

1. Pulse width limited by maximum junction temperature.
2. $L=0.5\text{mH}, V_{\text{DD}}=40\text{V}, R_G=25\Omega, \text{Starting } T_J=25^\circ\text{C}.$
3. Pulse test : Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristic Curves

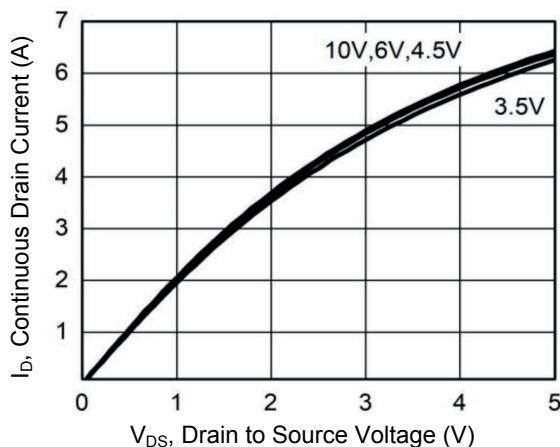


Figure 1. Output Characteristics

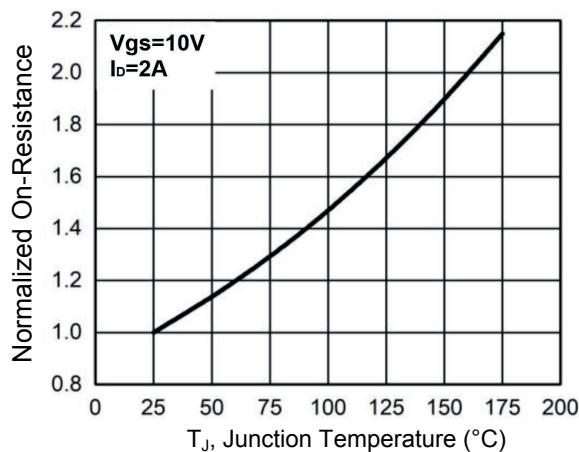


Figure 2. Normalized $R_{DS(ON)}$ vs. T_J

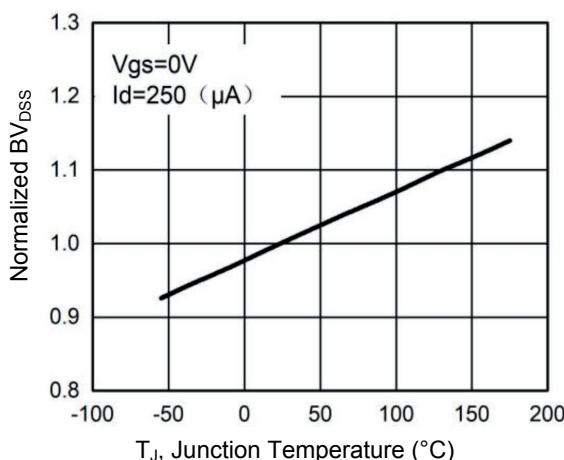


Figure 3. Normalized BV_{DSS} vs. T_J

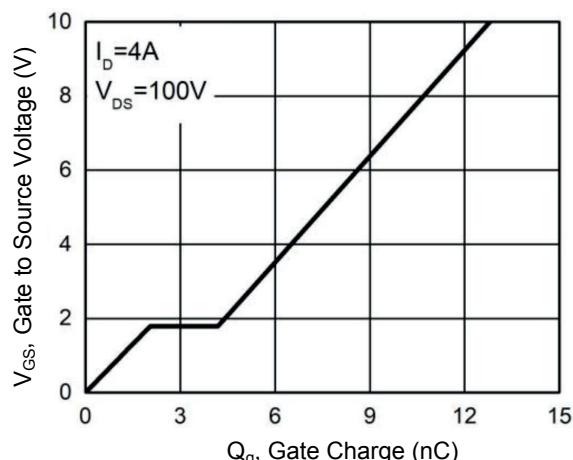


Figure 4. Gate Charge Waveform

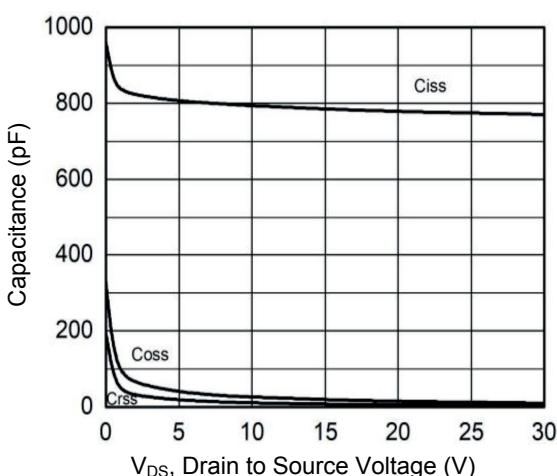


Figure 5. Capacitance Characteristics

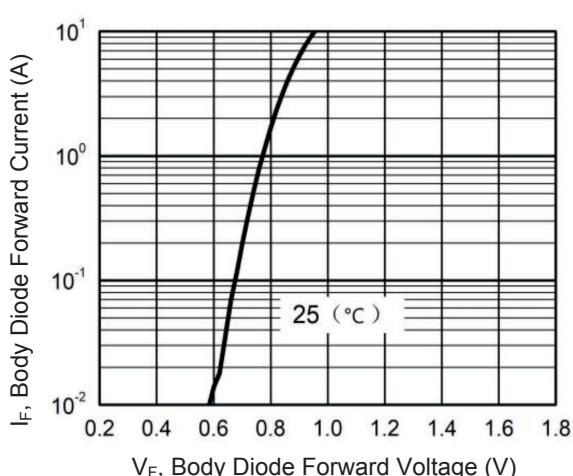
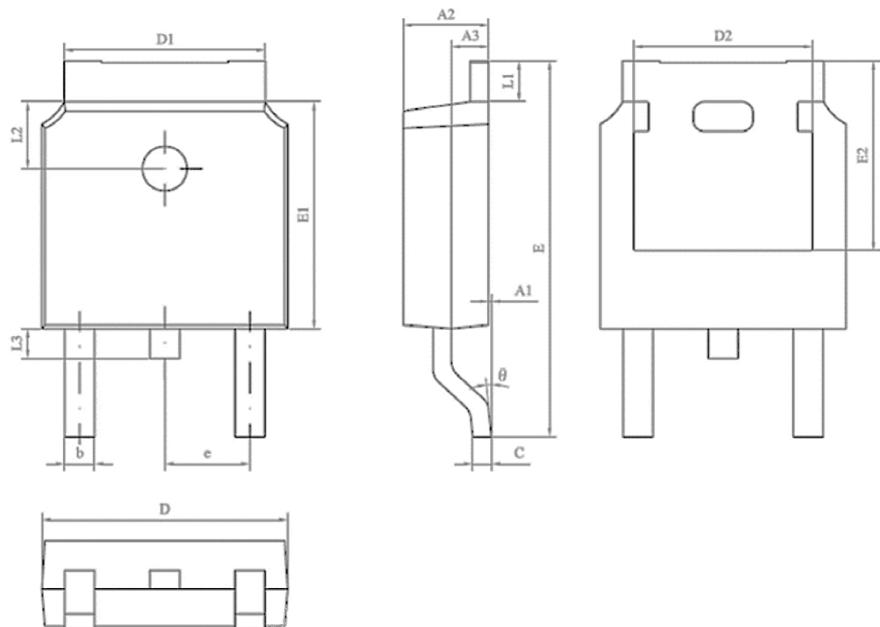


Figure 6. Body Diode Characteristics

Package Outline Dimensions TO-252 (DPAK)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A1	0.00	0.10	0.000	0.004
A2	2.20	2.40	0.087	0.094
A3	0.09	1.10	0.004	0.043
b	0.75	0.85	0.030	0.033
C	0.50	0.60	0.020	0.024
D	6.50	6.70	0.256	0.264
D1	5.30	5.50	0.209	0.217
D2	4.70	4.90	0.185	0.193
E	9.90	10.30	0.390	0.406
E1	6.00	6.20	0.236	0.244
E2	5.00	5.20	0.197	0.205
e	2.20	2.40	0.087	0.094
L1	0.90	1.25	0.035	0.049
L2	1.70	1.90	0.067	0.075
L3	0.60	1.00	0.024	0.039
θ	0°	8°	0°	8°

Order Information

Device	Package	Marking	Carrier	Quantity
GSFD2506	TO-252	D2506	Tape & Reel	2,500 pcs / Reel